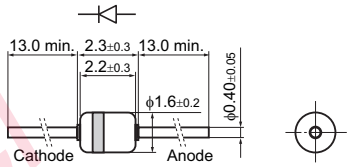
MA2C029W

Silicon epitaxial planar type

For reduced voltage and temperature compensation

Unit: mm



DO-34-A1 Package

■ Features

- High reliability achieved through combination of a planar type chip and glass sealing structure
- Easy mounting because of employing DO-35 (DHD) envelope
- Extremely small reverse current I_R
- Large power dissipation P_D
- Wide forward voltage V_F range

■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	6	V
Peak forward current	I_{FM}	100	mA
Power dissipation	P_D	150	mW
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	−55 to +150	°C

■ Electrical Characteristics $T_a = 25°C \pm 3°C$ *1

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward current	V_{F1}	$I_R = 10\ \mu A$	0.77			V
	V_{F2}	$I_F = 3$ mA	*2			
Reverse current	I_R	$V_R = 6$ V			1.0	μA
Temperature coefficient of forward voltage *3	$-\Delta V_F/V_T$	$I_F = 3$ mA		4.6		mV/°C

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. *1: The temperature must be controlled 25°C for V_F mesurement. V_F value measured at other temperature must be adjusted to V_F (25°C)

*2:

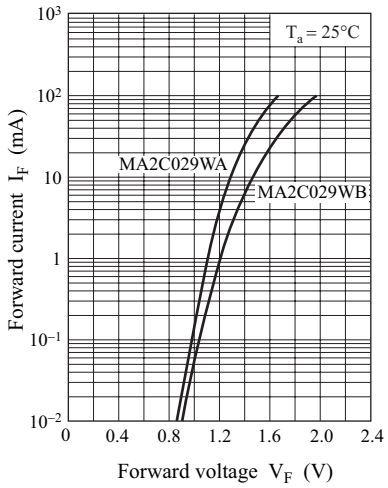
Type	V_F (V)
MA2C029WA	1.18 to 1.28
MA2C029WB	1.26 to 1.36

*3: $T_j = 25°C$ to 150°C

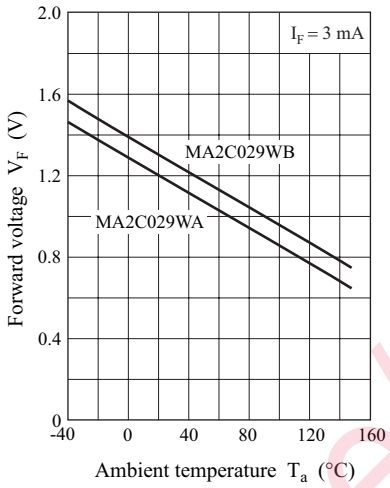
■ Cathode Indication

Type No.	MA2C029WA	MA2C029WB
Color	Light blue	Brown

I_F — V_F



V_F — T_a



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